AMENDMENTS

In the specification

On page 1, please insert the following heading and paragraph before "BACKGROUND OF THE INVENTION":

-- CROSS REFERENCE TO RELATED APPLICATIONS

This application is a continuation of U.S. Patent Application Serial No. 09/856,855, titled METHODS AND APPARATUS FOR HOLDING AND POSITIONING SEMICONDUCTOR WORKPIECES DURING ELECTROPOLISHING AND/OR ELECTROPLATING OF THE WORKPIECES, filed on November 24, 1999, which is a 371 of PCT/US99/28106, filed on November 24, 1999, which claims benefit of U.S. Provisional Patent Application Serial No. 60/110,136, filed on November 28, 1998, the entire contents of each of these applications are incorporated herein by reference. --

On page 3, please replace paragraph following "SUMMARY OF THE INVENTION" as follows:
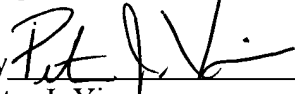
-- In one exemplary embodiment, a cell to electroplate and/or electropolish semiconductor wafers includes an electrolyte receptacle and a wafer chuck assembly. The cell also includes a first actuator configured to translate the wafer chuck assembly between a first position and a second position, where the wafer chuck assembly covers the electrolyte receptacle in the first position and retracts from the electrolyte receptacle in the second position. --

CONCLUSION

In the unlikely event that the transmittal letter is separated from this document and the Patent Office determines that an extension and/or other relief is required, applicant petitions for any required relief including extensions of time and authorizes the Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to **Deposit Account No. 03-1952** referencing docket no. 495152000402. However, the Commissioner is not authorized to charge the cost of the issue fee to the Deposit Account.

Dated: November 24, 2003

Respectfully submitted,

By

Peter J. Yim
    Registration No.: 44,417
MORRISON & FOERSTER LLP
425 Market Street
San Francisco, California 94105-2482
(415) 268-6373
Attorneys for Applicant